

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2977655

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
EUN HYE JUNG	08/04/2014
CHAN GYUN SHIN	08/04/2014
JONG CHEOL LIM	08/04/2014
NAM HYUN KIM	08/04/2014
RECEIVING PARTY DATA	
Name:	SAMSUNG SDI CO., LTD.
Street Address:	150-20 GONGSE-RO
Internal Address:	GIHEUNG-GU
City:	YONGIN-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	446-902
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14340709
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	7250.004
NAME OF SUBMITTER:	MELISSA B. PENDLETON
SIGNATURE:	/Melissa B. Pendleton/
DATE SIGNED:	08/12/2014
Total Attachments: 4	
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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies) EUN HYE JUNG CHAN GYUN SHIN JONG CHEOL LIM NAM HYUN KIM Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	2. Name and address of receiving party(ies) Name: <u>Samsung SDI Co., Ltd.</u> Internal Address: _____ Street Address: <u>150-20, Gongse-ro</u> <u>Giheung-gu</u> City: <u>Yongin-si</u> State: <u>Gyeonggi-do</u> Country: <u>South Korea</u> Zip: _____ Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
3. Nature of conveyance/Execution Date(s): Execution Date(s) <u>August 4, 2014</u> <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Joint Research Agreement <input type="checkbox"/> Government Interest Assignment <input type="checkbox"/> Executive Order 9424, Confirmatory License <input type="checkbox"/> Other	

4. Application or patent number(s): <input type="checkbox"/> This document is being filed together with a new application. A. Patent Application No.(s) <u>14/340,709</u> B. Patent No.(s) Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
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5. Name and address to whom correspondence concerning document should be mailed: Name: <u>Additon, Higgins & Pendleton, P.A.</u> Internal Address: _____ Street Address: <u>11610 N. Community House</u> <u>Road, Suite 200</u> City: <u>Charlotte</u> State: <u>NC</u> Zip: <u>28277-2199</u> Phone Number: <u>704-945-6700</u> Fax Number: <u>704-945-6735</u> Email Address: _____	6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____ <input type="checkbox"/> Authorized to be charged by credit card <input type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title)
8. Payment Information a. Credit Card Last 4 Numbers _____ Expiration Date _____ b. Deposit Account Number _____ Authorized User Name _____	

9. Signature: <u>/Melissa B. Pendleton/</u> <u>August 12, 2014</u> Melissa B. Pendleton Signature Date Name of Person Signing _____ Total number of pages including cover sheet, attachments, and documents: <u>4</u>
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Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1460, Alexandria, V.A. 22313-1460

ASSIGNMENT

WHEREAS, I, Eun Hye JUNG, a Korean citizen, with a mailing address of Compound 2group, 6F, R&D Center, 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; Chan Gyun SHIN, a Korean citizen, with a mailing address of EP Group, 6F, R&D Center, 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; Jong Cheol LIM, a Korean citizen, with a mailing address of Compound 3group, 6F, R&D Center, 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and Nam Hyun KIM, a Korean citizen, with a mailing address of 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Conductive Sheet Composition*, for which an U.S. application for United States Letters Patent was filed July 25, 2014, under Serial No. 12/340,709, and which application claims priority from a Korean application filed on July 25, 2013, under Serial No. 10-2013-0088484, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Samsung SDI Co., Ltd., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 150-20, Gongse-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-577, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby

acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries

and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

08.04, 2014 정 유 혜
Euñ Hye JUNG

8.4, 2014 신찬균
Chan Gyun SHIN

08.04, 2014 임종철
Jong Cheol LIM

08.04, 2014 김방현
Nam Hyun KIM